CALL FOR PAPERS

1973 IEEE Region Six Conference (Western Region); Minicomputers and Their Applications: May 2-4, 1973, Honolulu, Hawaii. Papers on minicomputer hardware, software, and applications are sought. Topics of interest include: architecture, input/output and peripherals, languages, management information systems, process control, timesharing, comparison of minicomputers, cost analysis, ocean engineering, education, medicine and business applications. Text and illustrations and a 200-300 word abstract in triplicate are to be submitted by January 12, 1973 to: Dr. Donald J. Grace, Kentron Hawaii, Ltd., 233 Keawe St., Honolulu, Hawaii 96813.

1973 Midwest Symposium on Circuit Theory: April 12-13, 1973, University of Waterloo, Waterloo, Ontario, Canada. Research papers on all aspects of circuit and system theory, control and communication theory, computer-aided circuit analysis and design are invited for presentation at the symposium and publication in the proceedings. Authors are requested to submit a title and summary before January 15, 1973 to: Prof. P.H. Roe, Systems Design Dept., University of Waterloo, Waterloo, Ontario, Canada.

Electronic Materials and Processing Symposium, Electrical/Electronics Insulation Conference: September 30-October 4, 1973, Palmer House, Chicago. (Session on Chip to Printed Circuit Connections will be cosponsored by the IEEE Computer Society Packaging Committee.) Papers are solicited on microwave materials, including plastic, ceramic, etc., aging and reliability, testing, cost-effective microwave systems, including effect of market price, quantity and reusability requirements on optimum material selection and production methods. Authors are requested to submit both a 35-word abstract and a 400-500 word summary by February 1, 1973 to: Mr. James D. Eaton, EIC Vice Chairman, Belden Corp., Tech. Research Center, POB 386, Geneva, Ill. 60134.

International Computing Symposium 1973: September 4-7, 1973, Davos, Switzerland. Papers (preferably in English) are sought in the areas of theoretical foundations of computer science, hardware and software systems, numerical analysis, scientific, technical and medical applications, administrative and social applications, and computers and education. Two copies of a 300-600 word abstract should be submitted by February 1, 1973 to: Dr. H. Lipps, Symposium Chairman, International Computing Symposium 1973, c/o CERN, CH-1211 Geneva, 23, Switzerland.

Third Data Communications Symposium: November 13-15, 1973, Tampa, Florida. This ACM/IEEE series (formerly entitled "Conferences on the Optimization of Data Communications") will be devoted to technical subjects related to the design, analysis, and operation of data networks. Topics include: packet, message and data switching, modems and multiplexers, sophisticated concentrators, network design and control, models and analytical techniques, standards, existing networks. Short abstracts should be submitted by March 1, 1973 to: Lt. Col. Philip H. Enslow Jr., 13178 Putnam Circle, Woodbridge, Va. 22191.

Second Texas Conference on Computing Systems: November 12-13, 1973, Austin, Texas. Tutorial, survey and research papers are solicited in any area of computing systems including: programming languages, reliability and diagnosis, computer communication and networks, operating systems, minicomputer systems, computer architecture, and data management. Authors are requested to submit a letter of intent to present a paper by June 1, 1973 to: Terry Welch, Dept of Electrical Engineering, University of Texas at Austin, Austin, Texas 78712.

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